### 3.3V, 7-Channel Analog Video Switch with Dual Control Logic

## Features

- Designed specifically to switch VGA signals
- 7-Channels for VGA signals (R,G,B, Hsync, Vsync, DDC Dat, and DDC CLK)
- 1st SEL can control RGBHV signals and 2nd SEL can control SCL/SDA signals
- $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}+/-10 \%$
- ESD tolerance on video I/O pins is up to 12 kV HBM per JEDEC standard and 8 kV contact per IEC61000-4-2 standard
- -3 dB BW of 1.0 GHz (typ)
- Low Xtalk, (-44dB typ)
- Low and Flat ON-STATE resistance $\left(\mathrm{R}_{\mathrm{on}}=3-\mathrm{Ohm}, \mathrm{R}_{\mathrm{on}}(\mathrm{Flat})\right.$ $=0.5 \mathrm{ohm}, \mathrm{typ}$ )
- Low input/output capacitance $(\mathrm{Con}=6.5 \mathrm{pF}$, typ)
- Packaging (Pb-free and Green):

$$
\begin{aligned}
& -32 \text {-contact TQFN (ZLE) } \\
& -28 \text {-contact TQFN (ZHE) }
\end{aligned}
$$

## Applications

- Routes physical layer signals for high bandwidth digital video


## Block Diagram

## Description

Pericom's PI3V712-A is a 7-channel video mux/demux used to switch between multiple VGA sources or end points. In a notebook application where analog video signals are found in both the notebook and the dock, a switch solution is required to switch between the two video port locations. With the high bandwidth of $\sim 1.0 \mathrm{GHz}$, the signal integrity will remain strong even through the long FR4 trace between the notebook and the docking station. In addition to high signal performance, the video signals are also protected against high ESD with integrated diodes to $\mathrm{V}_{\mathrm{DD}}$ and GND that will support up to 8 kV of contact ESD protection.

## Application

Routing VGA signals with low signal attenuation and high ESD protection.


## Pin Description (32-TQFN)

| Pin \# | Pin Name | Pin Type | Description |
| :---: | :---: | :---: | :---: |
| 1 | A0 | I/O | Bi-Directional Signal Pin |
| 2 | A1 | I/O | Bi-Directional Signal Pin |
| 3 | GND | Ground | Ground |
| 4 | Vdd | Power | 3.3V +/-10\% Power |
| 5 | A2 | I/O | Bi-Directional Signal Pin |
| 6 | A3 | I/O | Bi-Directional Signal Pin |
| 7 | A4 | I/O | Bi-Directional Signal Pin |
| 8 | SEL1 | I | Control Logic for channels $0,1,2,3$, and 4 |
| 9 | A5 | I/O | Bi-Directional Signal Pin |
| 10 | A6 | I/O | Bi-Directional Signal Pin |
| 11 | GND | Ground | Ground |
| 12 | 5B1 | I/O | Bi-Directional Signal Pin |
| 13 | 5B2 | I/O | Bi-Directional Signal Pin |
| 14 | 6B1 | I/O | Bi-Directional Signal Pin |
| 15 | 6B2 | I/O | Bi-Directional Signal Pin |
| 16 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 17 | 4B2 | I/O | Bi-Directional Signal Pin |
| 18 | 4B1 | I/O | Bi-Directional Signal Pin |
| 19 | 3B2 | I/O | Bi-Directional Signal Pin |
| 20 | 3B1 | I/O | Bi-Directional Signal Pin |
| 21 | 2B2 | I/O | Bi-Directional Signal Pin |
| 22 | 2B1 | I/O | Bi-Directional Signal Pin |
| 23 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 24 | 1B2 | I/O | Bi-Directional Signal Pin |
| 25 | 1B1 | I/O | Bi-Directional Signal Pin |
| 26 | 0B2 | I/O | Bi-Directional Signal Pin |
| 27 | 0B1 | I/O | Bi-Directional Signal Pin |
| 28 | GND | Ground | Ground |
| 29 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 30 | SEL2 | I | Control Logic for channels 5 and 6 |
| 31 | GND | Ground | Ground |
| 32 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |

## Pin Description (28-TQFN)

| Pin \# | Pin Name | Pin Type | Description |
| :---: | :---: | :---: | :---: |
| 1 | A0 | I/O | Bi-Directional Signal Pin |
| 2 | A1 | I/O | Bi-Directional Signal Pin |
| 3 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 4 | A2 | I/O | Bi-Directional Signal Pin |
| 5 | A3 | I/O | Bi-Directional Signal Pin |
| 6 | A4 | I/O | Bi-Directional Signal Pin |
| 7 | SEL1 | I | Control Logic for channels $0,1,2,3$, and 4 |
| 8 | A5 | I/O | Bi-Directional Signal Pin |
| 9 | A6 | I/O | Bi-Directional Signal Pin |
| 10 | 5B1 | I/O | Bi-Directional Signal Pin |
| 11 | 5B2 | I/O | Bi-Directional Signal Pin |
| 12 | 6B1 | I/O | Bi-Directional Signal Pin |
| 13 | 6B2 | I/O | Bi-Directional Signal Pin |
| 14 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 15 | 4B2 | I/O | Bi-Directional Signal Pin |
| 16 | 4B1 | I/O | Bi-Directional Signal Pin |
| 17 | 3B2 | I/O | Bi-Directional Signal Pin |
| 18 | 3B1 | I/O | Bi-Directional Signal Pin |
| 19 | 2B2 | I/O | Bi-Directional Signal Pin |
| 20 | 2B1 | I/O | Bi-Directional Signal Pin |
| 21 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 22 | 1B2 | I/O | Bi-Directional Signal Pin |
| 23 | 1B1 | I/O | Bi-Directional Signal Pin |
| 24 | 0B2 | I/O | Bi-Directional Signal Pin |
| 25 | 0B1 | I/O | Bi-Directional Signal Pin |
| 26 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |
| 27 | SEL2 | I | Control Logic for channels 5 and 6 |
| 28 | Vdd | Power | $3.3 \mathrm{~V}+/-10 \%$ Power |

Pin Description 2


## Maximum Ratings

(Above which useful life may be impaired. For user guidelines, not tested.)

$$
\begin{aligned}
& \text { Storage Temperature.................................... }-65^{\circ} \mathrm{C} \text { to }+150^{\circ} \mathrm{C} \\
& \text { Supply Voltage to Ground Potential................ }-0.5 \mathrm{~V} \text { to }+4.0 \mathrm{~V} \\
& \text { DC Input Voltage....................................................................................................................................................................................... }
\end{aligned}
$$

## Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

## Truth Table

| Input SELx $^{1}$ | Input/Output An | Function |  |
| :---: | :---: | :---: | :---: |
| L | $\mathrm{nB}_{1}$ | $\mathrm{~A}_{\mathrm{n}}=\mathrm{nB}_{1}$ | $\mathrm{nB}_{2}$ high impedance mode |
| H | $\mathrm{nB}_{2}$ | $\mathrm{~A}_{\mathrm{n}}=\mathrm{nB}_{2}$ | $\mathrm{nB}{ }_{1}$ high impedance mode |

Notes:

1. SEL 1 controls bit0 to bit 4; SEL 2 controls bit 5 to bit 6

DC Electrical Characteristics for Video Switching over Operating Range
$\left(\mathrm{T}_{\mathrm{A}}=-40^{\circ} \mathrm{C}\right.$ to $\left.+85^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V} \pm 10 \%\right)$

| Parameters | Description | Test Conditions ${ }^{(1)}$ | Min. | Typ. ${ }^{(2)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}_{\text {IH }}$ | Input HIGH Voltage | Guaranteed HIGH level | 2 | - | - | V |
| $\mathrm{V}_{\text {IL }}$ | Input LOW Voltage | Guaranteed LOW level | $-0.5$ | - | 0.8 |  |
| $\mathrm{V}_{\text {IK }}$ | Clamp Diode Voltage | $\mathrm{V}_{\mathrm{DD}}=$ Max., $\mathrm{I}_{\text {SELx }}=-18 \mathrm{~mA}$ | - | $-0.8$ | -1.2 |  |
| $\mathrm{I}_{\mathrm{IH}}$ | Input HIGH Current | $\mathrm{V}_{\mathrm{DD}}=$ Max., $\mathrm{V}_{\text {SELx }}=\mathrm{V}_{\text {DD }}$ | - | - | $\pm 5$ | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\text {IL }}$ | Input LOW Current | $\mathrm{V}_{\mathrm{DD}}=$ Max., $\mathrm{V}_{\text {SELx }}=\mathrm{GND}$ | - | - | $\pm 5$ |  |
| $\mathrm{I}_{\text {OFF }}$ | Power Down Leakage Current | $\mathrm{V}_{\mathrm{DD}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{B}}=0 \mathrm{~V}, \mathrm{~V}_{\mathrm{A}} \leq 3.6$ | - | - | $\pm 5$ |  |
| $\mathrm{R}_{\mathrm{ON}}$ | Switch On-Resistance(3) | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=\text { Min., } 0 \mathrm{~V} \leq \mathrm{V}_{\text {input }} \leq 1.2 \mathrm{~V}, \\ & \mathrm{I}_{\text {input }}=-40 \mathrm{~mA} \end{aligned}$ | - | 3 | - | $\Omega$ |
| $\mathrm{R}_{\text {FLAT(ON) }}$ | On-Resistance Flatness(4) | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=\mathrm{Min} ., \mathrm{V}_{\text {input }} @ 0 \mathrm{~V} \text { and } 1.2 \mathrm{~V}, \\ & \mathrm{I}_{\text {input }}=-40 \mathrm{~mA} \end{aligned}$ | - | 0.5 | - |  |
| $\Delta \mathrm{R}_{\mathrm{ON}}$ | On-Resistance match from center ports to any other port (4) | $\begin{aligned} & \mathrm{V}_{\mathrm{DD}}=\text { Min., } 0 \mathrm{~V} \leq \mathrm{V}_{\text {input }} \leq 1.2 \mathrm{~V}, \\ & \mathrm{I}_{\text {input }}=-40 \mathrm{~mA} \end{aligned}$ | - | 0.1 | 1 |  |

Capacitance $\left(\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{f}=1 \mathrm{MHz}\right)$

| Parameters ${ }^{(4)}$ | Description | Test Conditions ${ }^{(1)}$ | Typ. ${ }^{(2)}$ | Units |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{C}_{\text {IN }}$ | Input Capacitance | $\mathrm{V}_{\text {SELx }}=0 \mathrm{~V}$ | 3.1 | pF |
| Coff | Port I Capacitance, Switch OFF |  | 2.4 |  |
| CON | Switch Capacitance, Switch ON |  | 6.5 |  |

## Notes:

1. For max. or min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ ambient and maximum loading.
3. Measured by the voltage drop between $A$ and $B$ pins at indicated current through the switch. On-Resistance is determined by the lower of the voltages on the two (A \& B) pins.
4. This parameter is determined by device characterization but is not production tested.

## Power Supply Characteristics

| Parameters | Description | Test Conditions ${ }^{(\mathbf{1 )}}$ | Min. | Typ. ${ }^{(\mathbf{2})}$ | Max. | Units |
| :--- | :--- | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{I}_{\mathrm{CC}}$ | Quiescent Power Supply Current | $\mathrm{V}_{\mathrm{DD}}=$ Max., $\mathrm{V}_{\mathrm{IN}}=$ GND or $\mathrm{V}_{\mathrm{DD}}$ | - | - | 500 | $\mu \mathrm{~A}$ |

Notes:

1. For max. or min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Typical values are at $\mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ ambient and maximum loading.

## Dynamic Electrical Characteristics Over the Operating Range ( $\mathrm{T}_{\mathrm{A}}=-40^{\circ}$ to $+85^{\circ} \mathrm{C}, \mathrm{V}_{\mathrm{DD}}=3.3 \mathrm{~V} \pm 10 \%, \mathrm{GND}=0 \mathrm{~V}$ )

| Parameters | Description | Test Conditions |  | Min. | Typ. ${ }^{(2)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{X}_{\text {TALK }}$ | Crosstalk | $\mathrm{f}=250 \mathrm{MHz}$, See Fig. 2 |  | - | -44 | - |  |
| OIRR | OFF Isolation | $\mathrm{f}=250 \mathrm{MHz}$, See Fig. 3 |  | - | -40 | - |  |
| BW | Bandwidth -3 dB | See Fig. 1 |  | - | 1.0 | - | GHz |
| $\mathrm{I}_{\text {LOSS }}$ | Insertion Loss | with 75-Ohm load | Freq $=10 \mathrm{MHz}(\mathrm{VGA})$ |  | 0.45 |  | dB |
|  |  |  | Freq $=100 \mathrm{MHz}$ (XGA) |  | 0.5 |  |  |
|  |  |  | Freq $=300 \mathrm{MHz}$ (UXGA) |  | 1.1 |  |  |

## Switching Characteristics

| Parameters | Description | Min. | Typ. ${ }^{(2)}$ | Max. | Units |
| :---: | :---: | :---: | :---: | :---: | :---: |
| tpd | Propagation Delay (2,3) | - | 0.25 |  | ns |
| $\mathrm{t}_{\text {PZH }}, \mathrm{t}_{\text {PZL }}$ | Line Enable Time - SELx to Input, Output | 0.5 | - | 8 |  |
| tr | Line Disable Time - SELx to Input, Output | 0.5 | - | 4 |  |
| $\mathrm{t}_{\text {SK }}(\mathrm{p})$ | Skew between opposite transitions of the same output $\left(\right.$ tpHL $\left.-\mathrm{t}_{\mathrm{PLH}}\right)(2)$ | - | 0.1 | 0.2 |  |

## Notes:

1. For max. or min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
2. Guaranteed by design.
3. The switch contributes no propagational delay other than the RC delay of the On-Resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25 ns for 10 pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interactions with the load on the driven side.

## Test Circuit for Electrical Characteristics ${ }^{(1)}$



Notes:

1. $\mathrm{C}_{\mathrm{L}}=$ Load capacitance: includes jig and probe capacitance.
2. $\quad \mathrm{R}_{\mathrm{T}}=$ Termination resistance: should be equal to $\mathrm{Z}_{\text {OUT }}$ of the Pulse Generator
3. All input impulses are supplied by generators having the following characteristics: $\mathrm{f}=10 \mathrm{MHz}, \mathrm{Z}_{\mathrm{O}}=50 \Omega, \mathrm{t}_{\mathrm{R}} \leq 2.5 \mathrm{~ns}, \mathrm{t}_{\mathrm{F}} \leq 2.5 \mathrm{~ns}$.
4. The outputs are measured one at a time with one transition per measurement.

## Switch Positions

| Test | Switch |
| :--- | :--- |
| t pLZ, $^{\|c\|}$ tPZL (output on I-side) | 6.0 V |
| t $_{\text {PHZ }}$, t $_{\text {PZH }}$ (output on I-side) | GND |
| Prop Delay | Open |

## Test Circuit for Dynamic Electrical Characteristics



Figure 1. Bandwidth -3dB Testing


Figure 2. Crosstalk Test Setup

HP4396B


Figure 3. Off Isolation Test Setup

## Switching Waveforms



Voltage Waveforms Propagation Delay Times


Output Skew - $\mathbf{t}_{\mathbf{S K}(0)}$


Voltage Waveforms Enable and Disable Times


Pulse Skew - $\mathbf{t s K}_{\text {SK }}$ (p)

## Applications Information

## Logic Inputs

The logic control inputs can be driven up to +3.6 V regardless of the supply voltage. For example, given a +3.3 V supply, the output enables or select pins may be driven low to 0 V and high to 3.6 V . Driving IN Rail-to-Rail ${ }^{\Omega}$ minimizes power consumption.

Rail-to-Rail is a registered trademark of Nippon Motorola, Ltd

## Packaging Mechanical: 28-Pin TQFN (ZH)

NOTE :

1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-220
4. RECOMMENDED LAND PATTERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA

| (4) PER/COM |  |
| :--- | :--- |
| Enabling Serial connectivity | DATE: 01/26/09 |
| DESCRIPTION: 28-Contact, Very Thin Quad Flat No-Lead, TQFN |  |
| PACKAGE CODE: ZH28 |  |
| DOCUMENT CONTROL \#: PD-2034 | REVISION: B |

09-0066

## Packaging Mechanical: 32-Pin TQFN (ZL)


NOTE :

1. ALL DIMENSIONS ARE IN mm . ANGLES IN DEGREES
2. COPLANARITY APPLIES TO THE EXPOSED THERMAL PAD AS WELL AS THE TERMINALS.
3. REFER JEDEC MO-22O.
4. RECOMMENDED LAND PATEERN IS FOR REFERENCE ONLY.
5. THERMAL PAD SOLDERING AREA

| (4) PERICOM ${ }^{\circ}$ <br> Enabling Serial Connectivity | DATE: 10/09/09 |
| :---: | :---: |
| DESCRIPTION: 32-contact, Thin Fine Pitch Quad Flat No-Lead (TQFN) |  |
| PACKAGE CODE: ZL (ZL32) |  |
| DOCUMENT CONTROL \#: PD-2044 | REVISION: A |

09-0125

## Ordering Information

| Ordering Code | Package Code | Package Description |
| :--- | :---: | :--- |
| PI3V712-AZHE | ZH | Pb-free \& Green, 28-pin TQFN |
| PI3V712-AZLE | ZL | Pb-free \& Green, 32-pin TQFN |

## Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packaging/
- "E" denotes Pb-free and Green
- Adding an " X " at the end of the ordering code denotes tape and reel packaging

